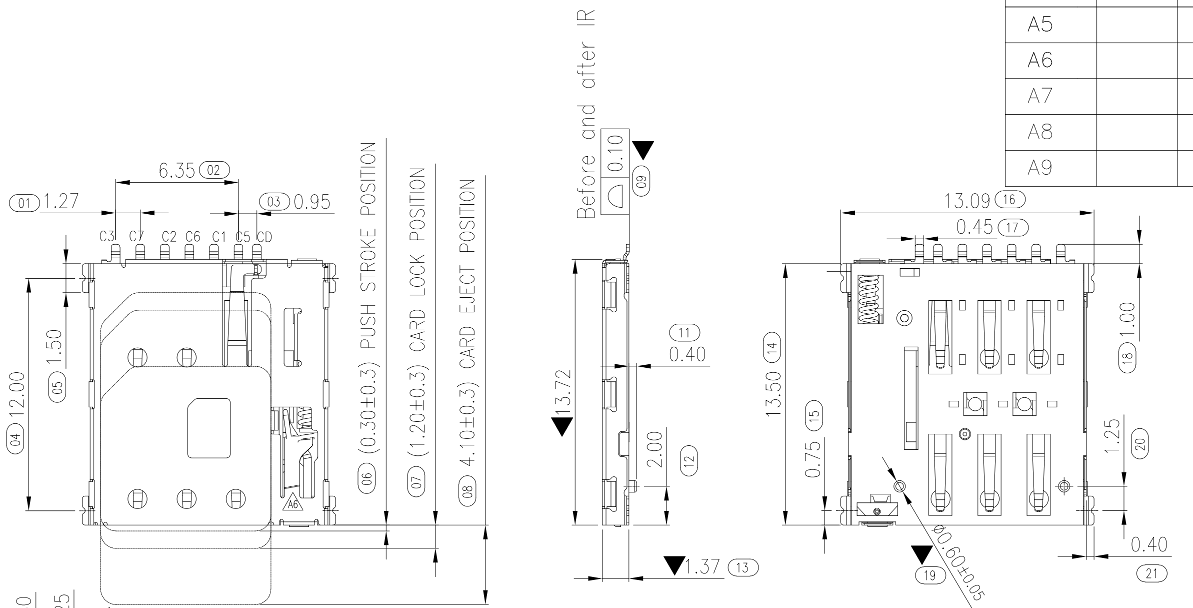
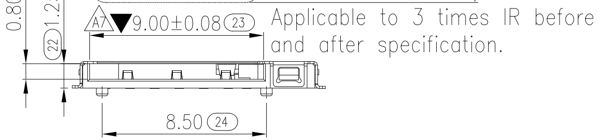
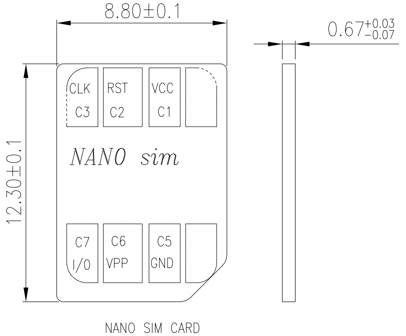
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2016/10/27	Phebe Su
A1.A2			Update.Change housing	2016/10/28.2016/12/22	Phebe Su
A3.A4			Modify.Change	2017/06/06.2017/07/07	Phebe Su
A5			Add the focus size mark	2017/12/01	Phebe Su
A6			Change angle of Slider	2017/12/07	Summer Wang
A7			Change 8.90 to 9.0±0.08	2018/01/10	Phebe Su
A8			Add notes	2018/11/30	Summer Wang
A9			Correct bottom view	2019/05/17	Phebe Su

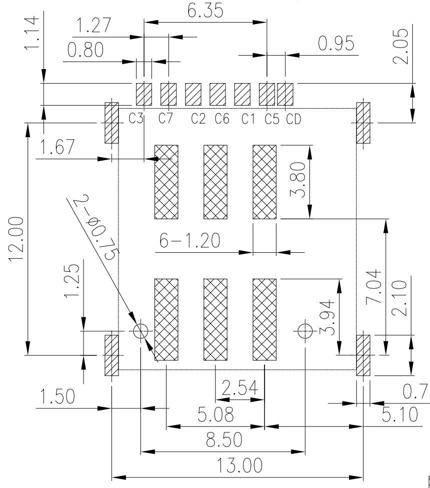




Applicable to 3 times IR before and after specification.



NANO SIM CARD



RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

▨ PAD

▦ KEEP OUT AREA

Specification:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0. Black

Contact: Copper Alloy

SHELL: STANLESS STEEL

PLATING:

Contact Area: Gold flash.

Solder Area: Gold flash plated. Under plate: nickel.

Shell: Nickel plated over all.

Solder Area: Gold flash.

Electrical:

Current Rating :1.0A max.

Voltage Rating :30V

Ambient Temperature Range :-40° C~+85° C

Storage Temperature Range :-40° C~+85° C

Humidity: 80% R.H. Max.

Contact Resistance:50mΩmax.

Insulation Resistance:1000MΩ MIN 500V DC

Mating Cycles:5,000 Insertions

Solder ability:260+0/-5° C.30±10s.

Performance:

Mating force: 5.7 N

Unmating force: 2.1 N

Pop-up force: 6.32 N

Add the focus size mark ▼

MATRIX PART NO:

MSM - 01 - 01 - 06 - 13 - 23

MSM: Matrix NANO SIM

01: Push
02: Non-Push

Plating
01: G/F
30: 30u

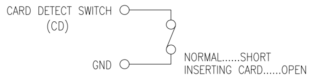
Pin number
06: 6pin

Height

Series Number

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



NORMAL......SHORT
INSERTING CARD......OPEN

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2019/05/17	PART NAME: NANO-SIM PUSH/PUSH 1.37H	
	CHECKED BY: Vicky Hsieh	DATE : 2019/05/17	PART NO.	MSM-01-01-06-13-23
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2019/05/17	MOLD NO.	NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2019/05/17	DRAW NO.	
			SHEET NO.	1 OF 1